

### Short Bio

Dr Tarapasanna Dash was born in the year 1985 at Remuna, Balasore District, Odisha, India. He graduated B.Tech in Electronics and Telecommunication Engineering, in 2009 from Biju Patnaik University of Technology (BPUT), Odisha, and obtained his M.Tech degree from IIT Kharagpur in Electronics and Communication Engineering in 2012. He completed his Ph. D from Siksha O Anusandhan University in 2019 in the area of Advance Electronic Devices. He is having more than 13 years of teaching experience. He has published more than 80 international publications in various international Journals and Conferences. He has authored around 10 book chapters in different edited books and co-authored a book “Stress and Strain Engineering at Nanoscale in Semiconductor Devices”. He has 3 patents to his credit.

He is a reviewer of IEEE Transactions on Electron Devices, IEEE Electron Device Letter, IOP, Springer, Wiley, Elsevier, Springer nature, and many publishers of international repute. He was listed in the Golden List of Reviewers by IEEE Transaction on Electron Devices in the year 2020. He has contributed as an author, reviewer, organizing member, TCP member, and advisor, session chairs in many international conferences like INDICON, ODICON, WIECON, EDKCON, MOS-AK , DevIC, IWPSD, MAMI, AECSS, and many more in India, and EICE-2021, AEM-2022, and CITIC-2022 in abroad. He has also edited the volume of the International Conference in Advances in Power, Signal, and Information Technology (APSIT-2021).

He is a Life Member of the Odisha Physical Society, Senior Member of IEEE, IEEE Electron Devices Society, International Roadmap for Devices and Systems (IRDS) Community, and IEEE Young Professionals, respectively. He was also appreciated as a mentor by CSIR-Summer Research Training Program (CSIR-SRTP-2020).

He was a key contributor in the development of the Microelectronics Fabrication Lab and Device Simulation Lab at Siksha O Anusandhan University. His research interests are in the field of advanced nanoscale device design, simulation, modelling, and stress/strain analysis in nanoscale devices.

Besides his technical contribution, he is also contributing towards the development of holistic value-based education in association with AICTE, and UGC as per the directives of NEP 2020, through ONLINE and OFFLINE workshops as /Resource Person/ Facilitator/Volunteer at national and regional levels.